L Number	Hits	Search Text	DB	Time stamp
9	2	6185815.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:02
10	47	("Re34615" | "3337941" | "4144449" | "4346293" | "4351264" | "4378134" | "4383359" | "4584047" | "4610083" | "4615093" | "4819326" | "4938653" | "5049029" | "5150423" | "5157734" | "5191693" | "5195234" | "5213653" | "5248362" | "5249239" | "5275657" | "5278634" | "5289625" | "5309223" | "5311304" | "5342460" | "5380099" | "5400497" | "5415693" | "5459794" | "5475919" | "5488771" | "5499756" | "5515600" | "5516026" | "5547537" | "5559727" | "5564188" | "5592562" | "5650081" | "5669970" | "5708419" | "5715594" | "5735040" | "5788379" | "5885052" | "6077022").PN.	USPAT	2004/07/07 15:00
11	8	flip adj chip near device and drive near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:42
12	251	flip adj chip near device and drive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:07
13	13	flip adj chip near device and drive and 29/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:33
14	36	("3317106" | "3692225" | "3938722" | "4084315" | "4489821" | "4626167" | "4768702" | "4776080" | "4878610" | "4921397" | "4980971" | "5022580" | "5044072" | "5054991" | "5084959" | "5113565" | "5115559" | "5233745" | "5311304" | "5351876" | "5368217" | "5370301" | "5377897" | "5454160" | "5460320" | "5462217" | "5482198" | "5535526" | "5579980" | "5743005" | "5744869" | "5759268" | "5768759" | "5864943" | "5870820" | "5992013").PN.	USPAT	2004/07/07 15:13
15	4	("4738025" | "4912843" | "4922434" | "4980971").PN.	USPAT	2004/07/07 15:21
16	4	("4342090" | "4598456" | "4663658" | "4675993").PN.	USPAT	2004/07/07 15:22

17	7	("3815204" | "4127936" | "4146924" | "4305130" | "4396945" | "4412293" | "4472668").PN.	USPAT	2004/07/07 15:24
18	106	4146924.URPN.	USPAT	2004/07/07 15:31
19	0	flip adj chip near device and drive and parallelogram near construction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
20	0	flip adj chip near device and drive and parallelogram	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
21	7965	Hartmann .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
22	1056	Hartmann .inv. and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
23	0	Hartmann .inv. and apparatus near flip adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:35
24	0	Hartmann .inv. and apparatus near flip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:35
25	3	Hartmann .inv. and apparatus and flip near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:35
26	1	1256974.URPN.	USPAT	2004/07/07 15:36
27	9	mounting near device and drive near system and (29/739; 29/740 ; 29/741 ; 198/468.4 ; 198/468.2 ; 414/752 ; 414/753 ; 414/751 ; 414/225 ; 414/226 ; 414/744.6).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:00
28	2	4601627.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:00

29	2	5049029.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:01
30	2	5084959.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:13
31	38	5084959.URPN.	USPAT	2004/07/07 16:02
32	7	("4598456" | "5084959" | "5115559" | "5172468" | "5206985" | "5420691" | "5456001").PN.	USPAT	2004/07/07 16:06
33	4	("4738025" | "4912843" | "4922434" | "4980971").PN.	USPAT	2004/07/07 16:08
34	7	("4342090" | "4628464" | "4641257" | "4720635" | "4723221" | "4737845" | "4780617").PN.	USPAT	2004/07/07 16:09
35	3	("3986007" | "4017721" | "4146924").PN.	USPAT	2004/07/07 16:10
36	8	("3216311" | "3454169" | "3589134" | "3669549" | "3804270" | "3850313" | "3888362" | "3890552").PN.	USPAT	2004/07/07 16:12
37	31	die adj bond$3 near apparatus and flip near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:23
38	8	Hartmann near Dominik .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:15
39	18	("3467430" | "4318222" | "4404741" | "4867569" | "4887351" | "4951383" | "5018936" | "5033783" | "5093983" | "RE33974" | "5172468" | "5201696" | "5222293" | "5251266" | "5341563" | "5471742" | "5590456" | "6203082").PN.	USPAT	2004/07/07 16:19
40	17	("Re33974" | "3467430" | "4318222" | "4404741" | "4867569" | "4887351" | "4951383" | "5018936" | "5033783" | "5093983" | "5172468" | "5201696" | "5222293" | "5251266" | "5341563" | "5471742" | "5590456").PN.	USPAT	2004/07/07 16:22
41	7	die adj bond$3 near apparatus and flip near chip and (294/64.1; 294/66.2 ; 294/907 ; 29/720 ; 29/721 ; 29/740 ; 29/743 ; 269/21 ; 279/3 ; 414/737 ; 414/752 ; 901/40 ; 901/47).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:24

	Title	Current OR
1	Apparatus for placing a semiconductor chip as a flipchip on a substrate	29/740
2	Electric-component transferring apparatus, method of taking images of electric components, and electric-component mounting system	29/833
3	Electric-component transferring apparatus	29/740
4	Electronic component mounting device	29/740
5	Circuit-component mounting system	29/740
6	Electronic parts-mounting apparatus	29/740
7	Surface mounted component transport mechanism	29/740
8	Multi-lead component manipulator	318/568.11
9	Automatic part insertion machine	29/741

	Current XRef
1	29/739; 29/840
2	29/593; 29/740; 29/742; 29/743
3	29/741; 29/742; 29/743; 29/832; 29/833; 29/834; 29/DIG.44
4	29/721; 29/741; 29/743
5	198/586; 29/741; 29/832
6	29/741; 29/743; 294/64.1
7	29/759
8	29/741; 29/833; 294/86.4; 294/907; 318/568.16; 318/640; 414/730
9	198/345.1; 29/759; 29/836; 29/838